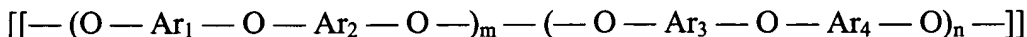


**Amendment to the Claims**

1. (currently amended): A poly(arylene ether) polymer including polymer repeat units of the following structure:

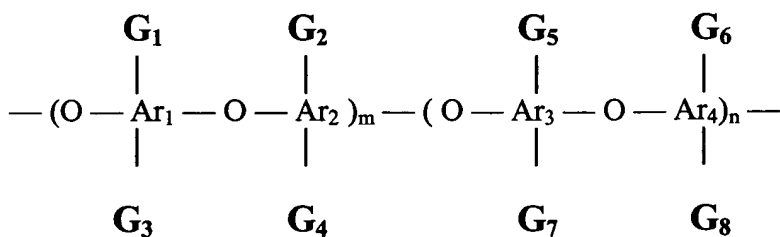
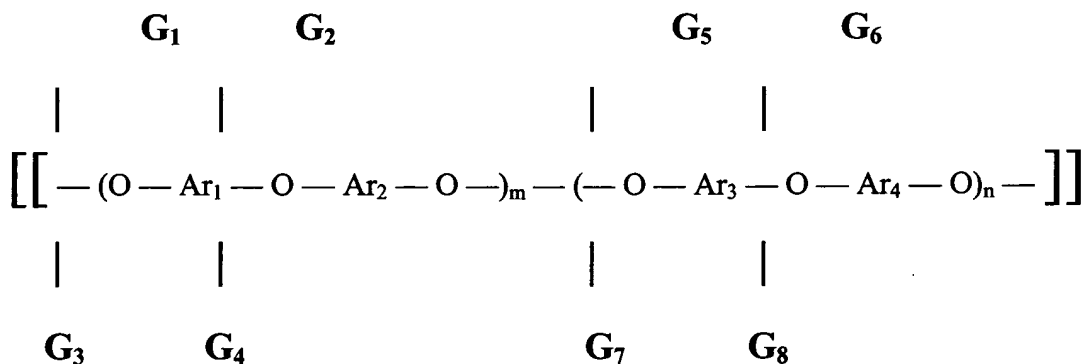


where Ar<sub>1</sub>, Ar<sub>2</sub>, Ar<sub>3</sub>, and Ar<sub>4</sub> are identical or different aryl radicals, m is 0.05 to 0.95, n is 1-m, and at least one of the aryl radicals is grafted to at least one hydroxyalkyl group.

2. (original): The polymer of claim 1, wherein one of the aryl radicals of the polymer repeat units is grafted to one hydroxyalkyl group.

3. (original): The polymer of claim 1, wherein at least one of the aryl radicals of the polymer repeat units is grafted to more than one hydroxyalkyl group.

4. (currently amended): The polymer of claim 1, wherein the polymer repeat units have the following structure:



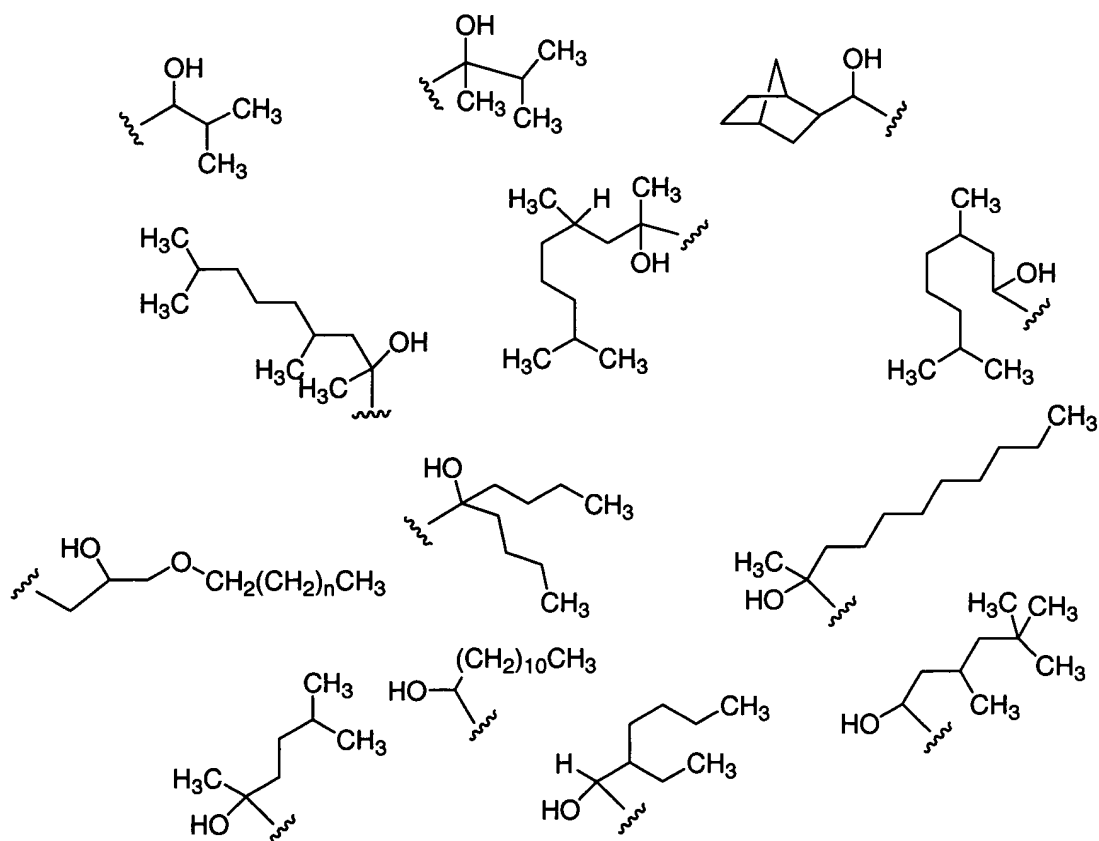
where  $G_1$ ,  $G_2$ ,  $G_3$ ,  $G_4$ ,  $G_5$ ,  $G_6$ ,  $G_7$  and  $G_8$  are identical or different species of the at least one hydroxyalkyl group.

5. (original): The polymer of claim 1, wherein an average number of hydroxyalkyl groups per polymer repeat unit is 0.01 to 8.0.

6. (original): The polymer of claim 5, wherein the average number of hydroxyalkyl groups per polymer repeat unit is 0.01 to 4.0.

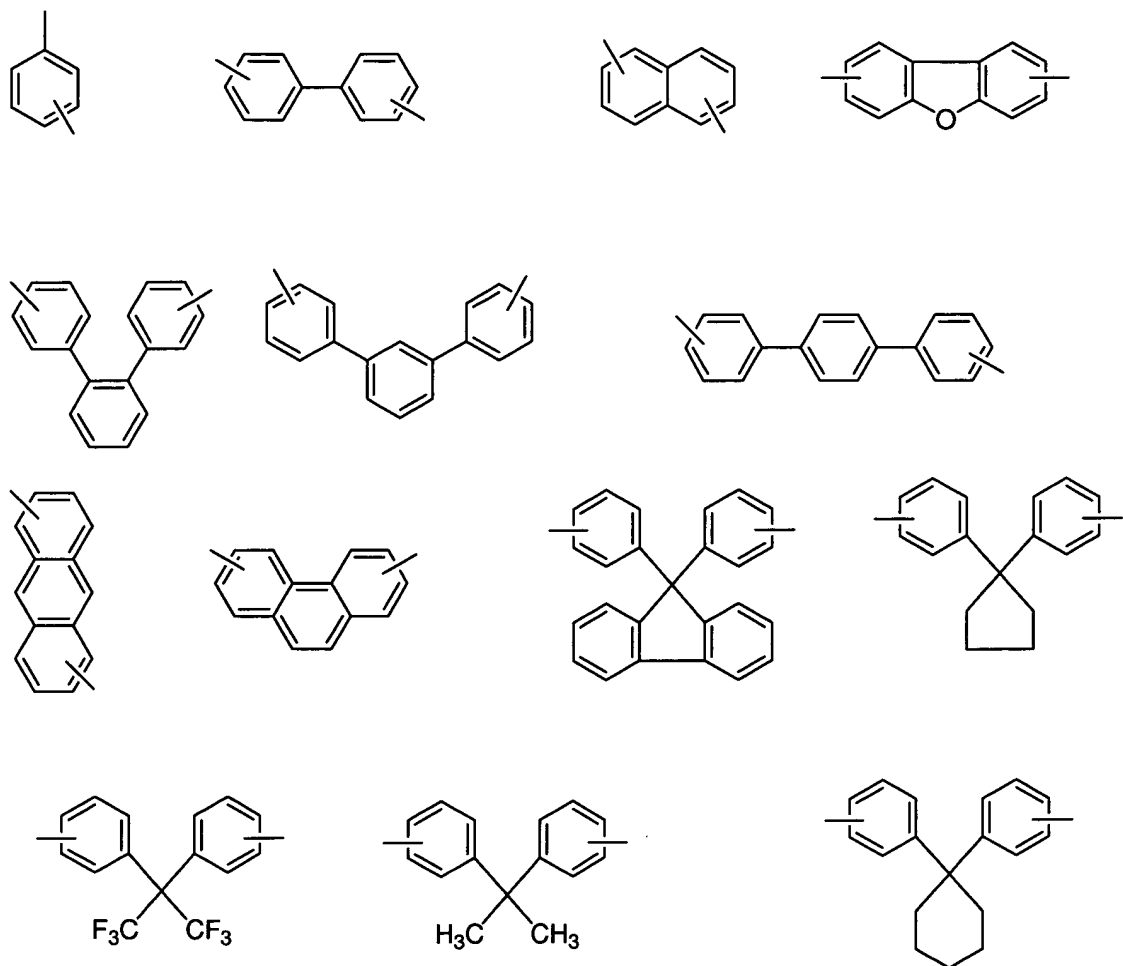
7. (original): The polymer of claim 5, wherein the average number of hydroxyalkyl groups per polymer repeat unit is 0.25 to 1.0.

8. (original): The polymer of claim 5, wherein the at least one hydroxyalkyl group is selected from the group consisting of:



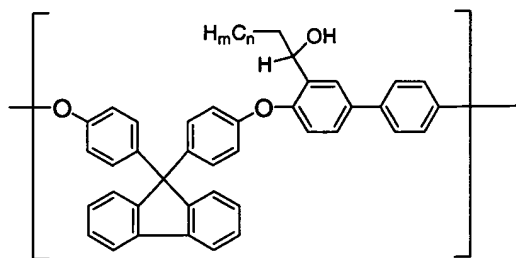
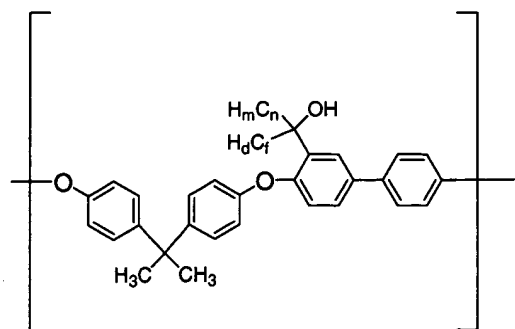
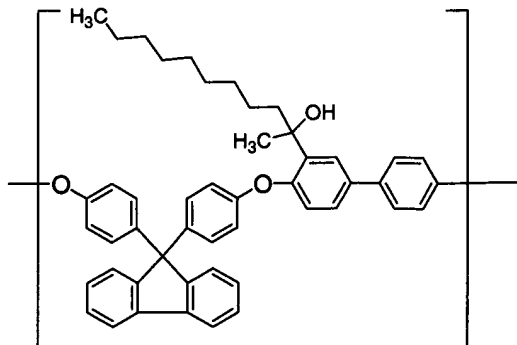
9. (original): The polymer of claim 5, wherein the at least one hydroxyalkyl group is 2-undecanol.

10. (original): The polymer of claim 5, wherein the aryl radicals are independently selected from the group consisting of:

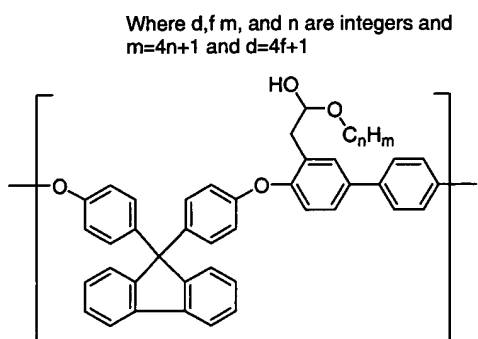


11. (original): The polymer of claim 5, wherein at least one of the aryl radicals is selected from the group consisting of 9,9-bis(4-hydroxyphenyl)-fluorene, 2,2-diphenylhexafluoropropene and 2,2-diphenylpropene.

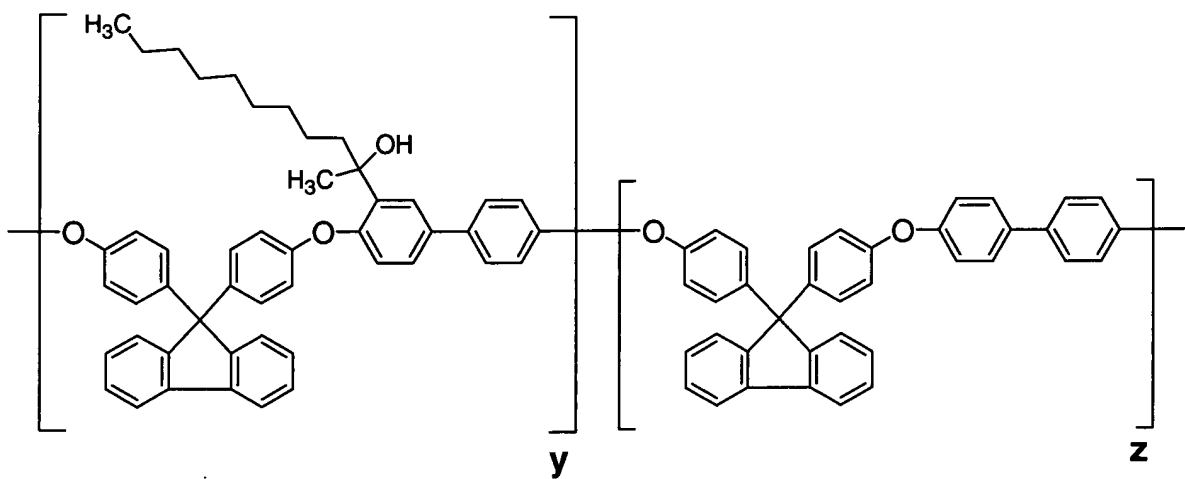
12. (original): The polymer of claim 5, wherein the polymer repeat units are independently selected from the group consisting of:



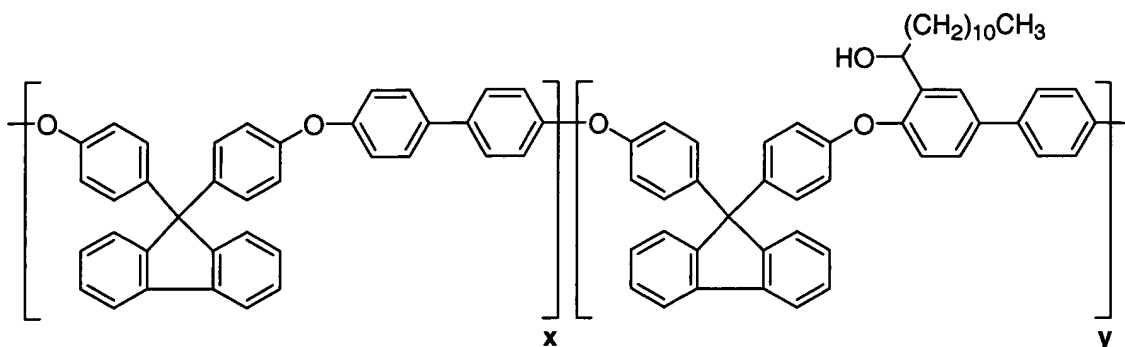
Where  $m$  and  $n$  are integers and  $m=4n+1$



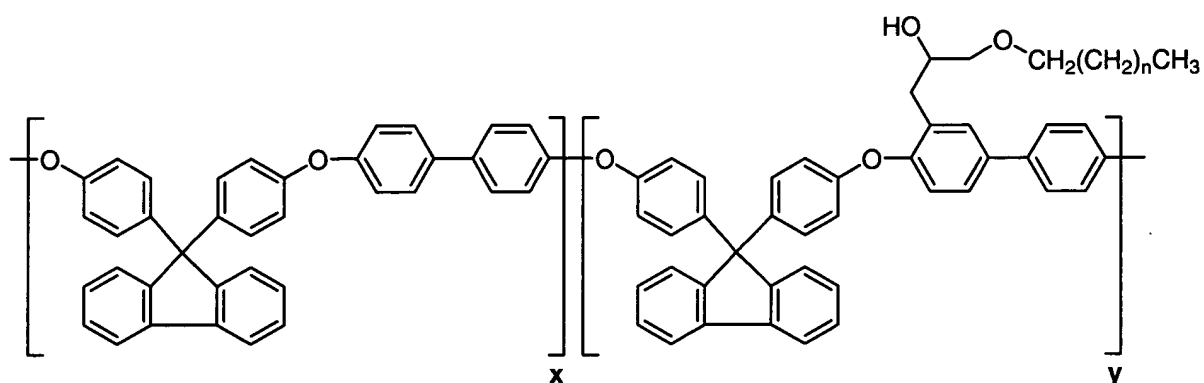
Where  $m$  and  $n$  are integers and  $m=4n+1$



where  $y + z = 1$  and  $y > 0.01$



where  $x + y = 1.0$  and  $y > 0.01$



where  $x + y = 1.0$  and  $y > 0.01$ .

13. (original): The polymer of claim 5 in an electrically conductive adhesive.
14. (original): The polymer of claim 13 in an integrated circuit.
15. (original): A composition comprising the polymer of claim 1.
16. (original): The composition of claim 15, further comprising a sufficient amount of conductive particles to render the composition suitable for use as an electrically conductive adhesive.
17. (original): The composition of claim 16, wherein the electrically conductive particles comprise at least one metal selected from the group consisting of copper, silver, nickel, gold, platinum and tin-bismuth alloy.
18. (original): The composition of claim 17, wherein each of the electrically conductive particles has a diameter less than 100 nm.
19. (original): The composition of claim 16, wherein the electrically conductive particles comprise carbon nanotubes and carbon black.
20. (original): The composition of claim 16, further comprising an adhesion promoter.

21. (original): The composition of claim 16, further comprising a plasticizer.
22. (original): The composition of claim 16, further comprising a chelating agent.
23. (original): The composition of claim 16, further comprising an epoxy resin system.
24. (original): The composition of claim 1, wherein the at least one hydroxyalkyl group is derived from an aliphatic aldehyde, an aliphatic ketone or an aliphatic glycidyl ether.
25. (withdrawn): An adhesion method comprising applying the composition of claim 16 between a first substrate and a second substrate to adhere the first substrate to the second substrate.
26. (original): An electronic package comprising the polymer of claim 1.
27. (original): The electronic package of claim 26, wherein the polymer is contained in a thermally conductive adhesive.
28. (original): The electronic package of claim 26, wherein the polymer is contained in a die attach adhesive.
29. (original): The electronic package of claim 26, wherein the polymer is contained in an encapsulant.